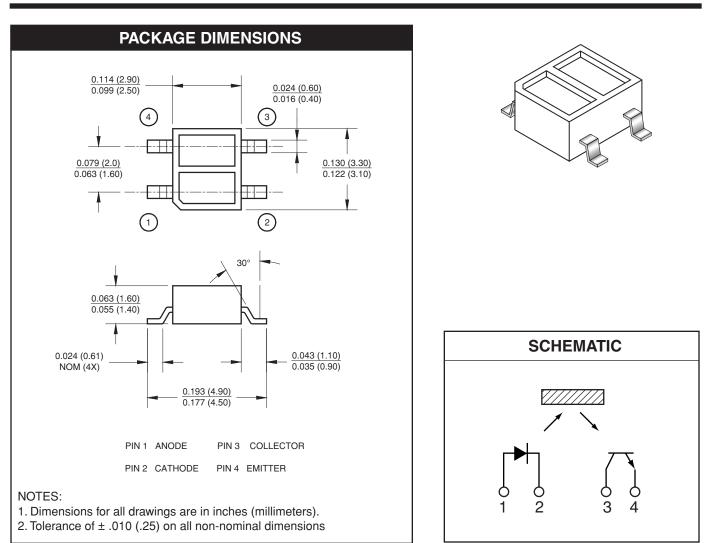


REFLECTIVE OBJECT SENSOR

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FEATURES

- Phototransistor output
- Tape and reel packaging
- No contact surface sensing
- Miniature package
- Lead form style: Gull Wing



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ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise specified)							
Parameter	Symbol	Rating	Units				
Operating Temperature	T _{OPR}	-25 to +85	°C				
Storage Temperature	T _{STG}	-30 to +100	°C				
Soldering Temperature (Iron) ^(2,3,4)	T _{SOL-I}	240 for 5 sec	°C				
Soldering Temperature (Flow) ^(2,3)	T _{SOL-F}	260 for 10 sec	°C				
EMITTER							
Continuous Forward Current	I _F	50	mA				
Reverse Voltage	V _R	5	V				
Peak Forward Current ⁽⁵⁾	I _{FP}	1	mA				
Power Dissipation ⁽¹⁾	PD	75	mW				
SENSOR							
Collector-Emitter Voltage	V _{CEO}	30	V				
Emitter-Collector Voltage	V _{ECO}	5	V				
Collector Current	Ι _C	20	mA				
Power Dissipation ⁽¹⁾	PD	50	mW				

ELECTRICAL / OPTICAL CHARACTERISTICS (T _A = 25°C unless otherwise specified)								
PARAMETER	TEST CONDITIONS	SYMBOL	MIN.	TYP.	MAX.	UNITS		
INPUT DIODE								
Forward Voltage	I _F = 20 mA	V _F	_	1.2	1.6	V		
Reverse Leakage Current	V _R = 5 V	I _R	_	_	10	μA		
Peak Emission Wavelength	I _F = 20 mA	λ _{PE}	_	940	_	nm		
OUTPUT TRANSISTOR								
Collector-Emitter Dark Current	$V_{CE} = 20 \text{ V}, \text{ I}_{F} = 0 \text{ mA}$	Ι _D	_	_	100	nA		
COUPLED								
On-State Collector Current	$I_{\rm F} = 20 \text{ mA}, V_{\rm CE} = 5 \text{ V}$	I _{C(ON)}	0.15	0.40	_	mA		
Saturation Voltage		V _{CE (SAT)}	—	—	0.3	V		
Rise Time	$\label{eq:VCC} \begin{split} V_{CC} &= 5 \text{ V}, \text{ I}_{C(ON)} = 100 \mu\text{A}, \\ \text{R}_L &= 1\text{K}\Omega \end{split}$	t _r	—	20	—	μs		
Fall Time		t _f	—	20	—			

NOTES:

- 1. Derate power dissipation linearly 1.33 mW/°C above 25°C.
- 2. RMA flux is recommended.

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- 3. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 4. Soldering iron 1/16" (1.6mm) from housing.
- 5. Pulse conditions: tp = $100 \ \mu s$; T = $10 \ ms$.



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TYPICAL PERFORMANCE CURVES

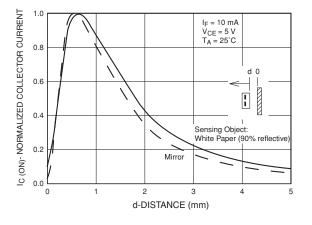
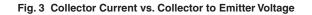


Fig. 1 Normalized Collector Current vs. Distance between device and reflector



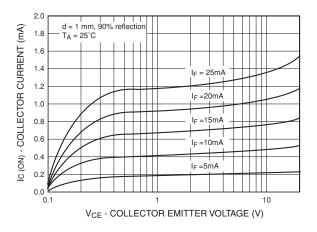


Fig. 4 Collector Emitter Dark Current (Normalized) vs. Ambient Temperature

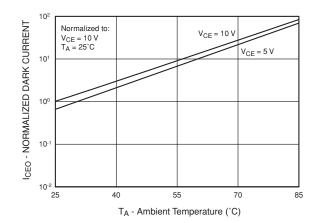


Fig. 2 Collector Current vs. Forward Current

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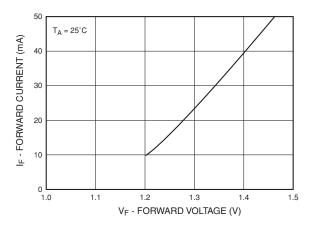


Fig. 5 Forward Current vs. Forward Voltage

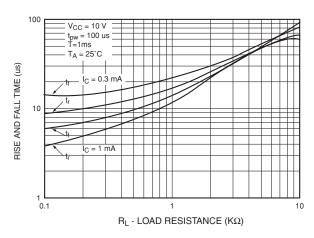
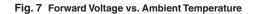
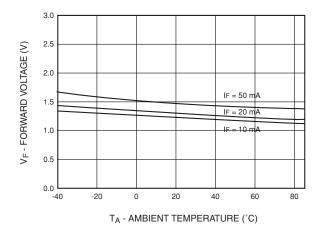


Fig. 6 Rise and Fall Time vs. Load Resistance







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